

Please replace the paragraph at Page 3, Column 6, lines 31-41 with the following amended paragraph:

92
In case the aforementioned individual portions are formed by the pressing, burrs 11 are left on the back of the cut portions. Since the leadframe 1 of the present embodiment is made such that the die pad 3 has a smaller area than that of the semiconductor chip 2 to be mounted thereon, the burrs 11, if any, on the face of the die pad 3 for mounting the semiconductor chip 2 will be unable to mount the chip 2. When the die pad 3 is to be pressed, therefore, it is pressed with its chip mounting [Face] face being directed upward so that the burrs 11 may be left on the back opposed to the chip mounting face.

93
Please replace the paragraph at Page 4, Column 8, lines 46-50 with the following amended paragraph:

As shown in FIG. 15, moreover, slightly wider small pads (or adhesion-applied portions) 20 than the suspension leads 4 may be formed around the die pad 5 so that the adhesive [1S] 15 may be applied to the individual principal faces of the die pad 3 and the small pads 20.

IN THE CLAIMS:

Please amend Claims 1, 6, 11, 13 and 14 as follows.

94
sub B1 > 1.(Once Amended) A semiconductor integrated circuit device comprising:
a semiconductor chip having a main surface including semiconductor elements and a plurality of bonding pads;